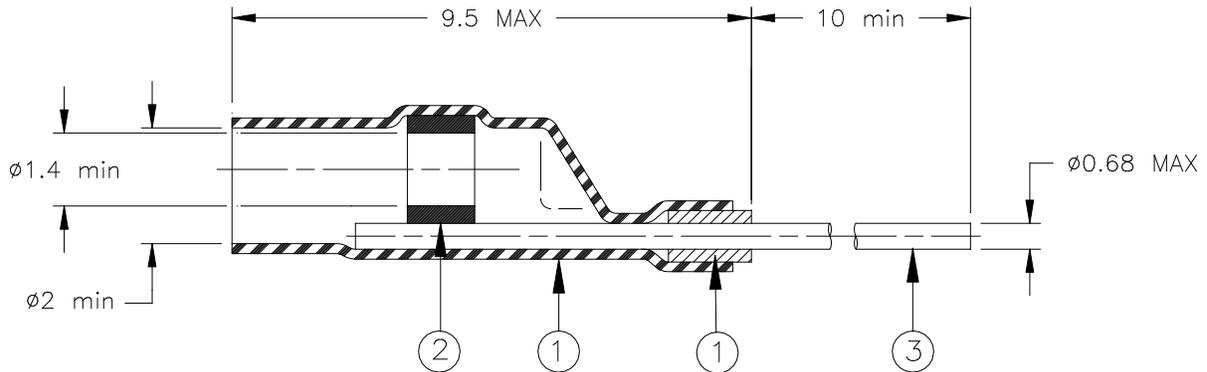


# CUSTOMER DRAWING



## MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:  
 SOLDER: TYPE Sn62 Pb36 Ag2 per ANSI-J-STD-006.  
 FLUX: TYPE ROL0 per ANSI-J-STD-004.
3. PIN: Cu/Sn-Pb/5b per ASTM B-579-73.

## APPLICATION

1. This controlled soldering device is designed for attaching a tin or silver plated, stranded AWG20, 22, 24, 26, 28, and 30 wire, having an insulation rating of at least +125°C, to a PC board with a 0.6mm diameter hole.  
 For AWG30 wires, a fold back with 10mm strip length is recommended.
2. Temperature range: -55°C to +150°C.

For best results, prepare the cable as shown:



|   |   |  |   |                          |                      |
|---|---|--|---|--------------------------|----------------------|
|  |   | <b>Raychem</b><br>THERMOFIT<br>DEVICES   | TITLE:<br><b>PINPAK*<br/>PCB TERMINATOR</b> |                          |                      |
| Unless otherwise specified dimensions are in millimeters.                           |   |  | DOCUMENT NO.:<br><b>B-801-15-01</b>         |                          |                      |
| TOLERANCES:<br>0.00 N/A<br>0.0 N/A<br>0 N/A   | ANGLES: N/A<br><br>ROUGHNESS IN<br>MICRON | TE Connectivity reserves the right to<br>amend this drawing at any time.<br>Users should evaluate the suitability<br>of the product for their application. | REV:<br><br>4                               | DATE:<br><br>09-Mar-2020 |                      |
| DRAWN BY:<br>M. FORONDA   | DATE:<br>22-Mar-1999                      | ECO:<br>ECO-20-003687  | SCALE:<br><br>NTS                           | SIZE:<br><br>A           | SHEET:<br><br>1 of 1 |

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